nexperia

Final Product Change Notification | 201811004F01

Issue Date: 31-Dec-2018
Effective Date: 15-Apr-2019
Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.
For detailed information we invite you to view this notification online

Management Summary
Change the die of the PBSSx350Z to the known 1160x810µm² pitch with glue back metal.

Change Category

[X] Wafer Fab Process	[X] Assembly Process	[ ] Product Marking	[ ] Test Location	[X] Design
[X] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

Change of die size and attach technology for PBSSx350Z

Details of this Change

Change die attach from eutectic to glue die attach and shrink of die size for 50 V, 3 A BISS transisators in SOT223.
Additionally PBSS5350Z will be released to use 8 inch wafer diameter.

Why do we Implement this Change
To increase flexibility and volume ramp-up.

Identification of Affected Products
The products using a chip from a 8 inch wafer can be identified by a marker on the die surface.
Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 31-Jan-2019
Production
Planned first shipment 15-Apr-2019

Impact

No impact to the products' functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201509006F02	08-Dec-2015	21-Mar-2016	Change of bond wire from Au to Cu for transistors in SOT223 package

Additional information

Affected products and sales history information: see attached file
Self qualification: view online

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Jan-2019. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 70 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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